

# RB521CS30L

100 mA low  $V_F$  MEGA Schottky barrier rectifier

Rev. 1 — 24 January 2011

Product data sheet

## 1. Product profile

### 1.1 General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD882 leadless ultra small Surface-Mounted Device (SMD) plastic package.

### 1.2 Features and benefits

- Average forward current:  $I_{F(AV)} \leq 100$  mA
- Reverse voltage:  $V_R \leq 30$  V
- Low forward voltage:  $V_F \leq 350$  mV
- Low reverse current:  $I_R \leq 10$   $\mu$ A
- AEC-Q101 qualified
- Leadless ultra small SMD plastic package

### 1.3 Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch Mode Power Supply (SMPS)
- Reverse polarity protection
- Low power consumption applications

### 1.4 Quick reference data

Table 1. Quick reference data



Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$I_{F(AV)}$	average forward current	square wave; $\delta = 0.5$ ; $f = 20$ kHz					
		$T_{amb} \leq 135$ °C	[1]	-	-	100	mA
		$T_{sp} \leq 145$ °C	-	-	-	100	mA
$I_R$	reverse current	$V_R = 10$ V	-	2	10	$\mu$ A	
$V_R$	reverse voltage		-	-	30	V	
$V_F$	forward voltage	$I_F = 10$ mA	[2]	-	280	350	mV

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.

[2] Pulse test:  $t_p \leq 300$   $\mu$ s;  $\delta \leq 0.02$ .

## 2. Pinning information

**Table 2. Pinning**

Pin	Description	Simplified outline	Graphic symbol
1	cathode	 <p>Transparent top view</p>	 sym001
2	anode		

[1] The marking bar indicates the cathode.

## 3. Ordering information

**Table 3. Ordering information**

Type number	Package		
	Name	Description	Version
RB521CS30L	-	leadless ultra small plastic package; 2 terminal; body 1.0 × 0.6 × 0.5 mm	SOD882

## 4. Marking

**Table 4. Marking codes**

Type number	Marking code
RB521CS30L	AR

## 5. Limiting values

**Table 5. Limiting values**

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit	
$V_R$	reverse voltage		-	30	V	
$I_{F(AV)}$	average forward current	square wave; $\delta = 0.5$ ; $f = 20$ kHz				
		$T_{amb} \leq 135$ °C	[1]	-	100	mA
		$T_{sp} \leq 145$ °C	-	-	100	mA
$I_{FSM}$	non-repetitive peak forward current	half sine wave; $t_p \leq 8.3$ ms	[2]	-	3	A

**Table 5. Limiting values ...continued**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit	
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ °C}$	[4][3]	-	315	mW
			[4][1]	-	565	mW
$T_j$	junction temperature		-	150	°C	
$T_{amb}$	ambient temperature		-65	+150	°C	
$T_{stg}$	storage temperature		-65	+150	°C	

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.

[2]  $T_j = 25\text{ °C}$  prior to surge.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[4] Reflow soldering is the only recommended soldering method.

## 6. Thermal characteristics

**Table 6. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1][2]				
			[3]	-	-	395	K/W
			[4]	-	-	220	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[5]	-	-	70	K/W

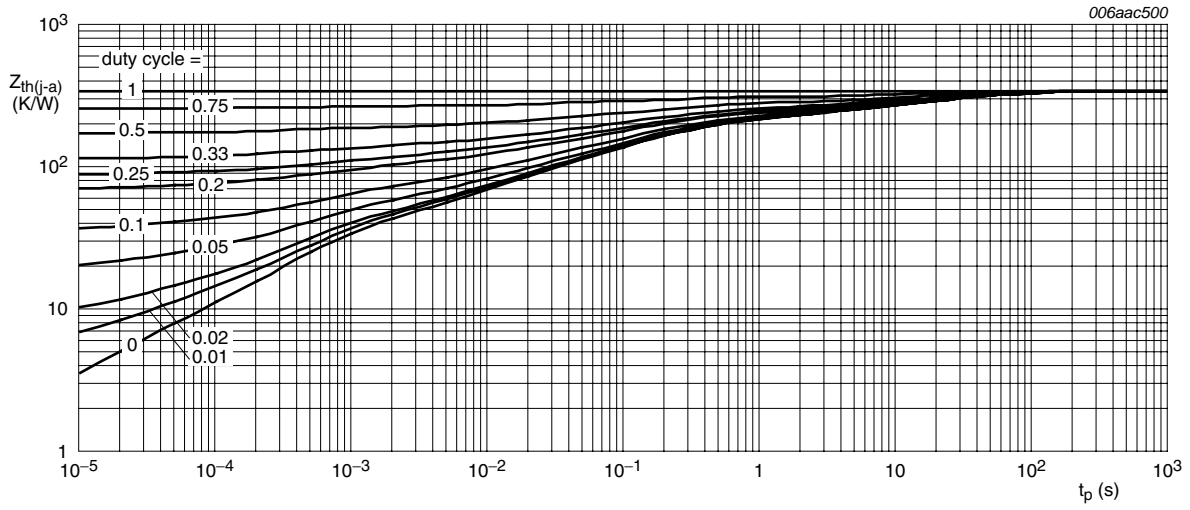
[1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses  $P_R$  are a significant part of the total power losses.

[2] Reflow soldering is the only recommended soldering method.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

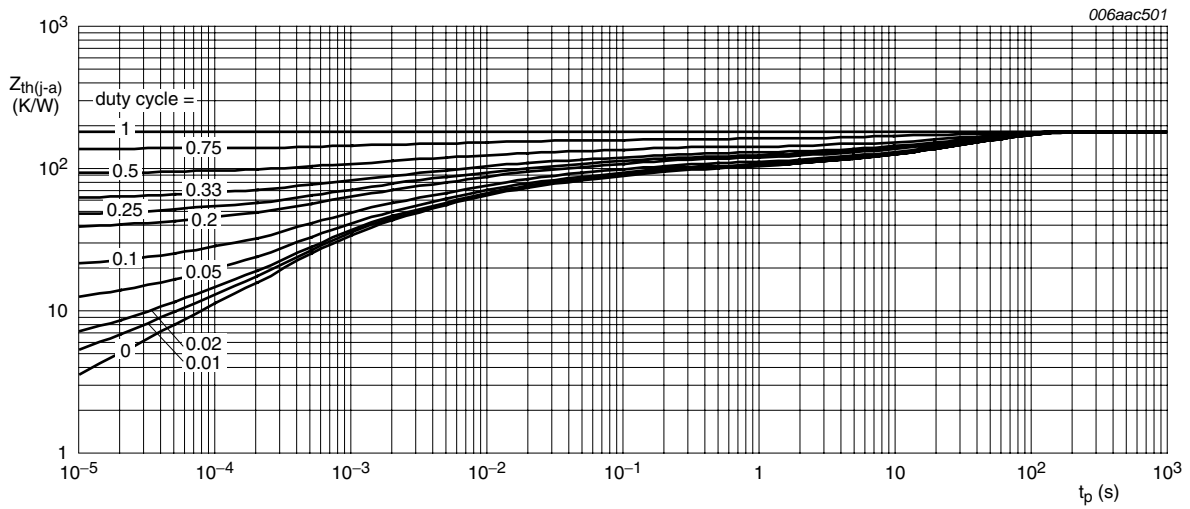
[4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.

[5] Soldering point of cathode tab.



FR4 PCB, standard footprint

**Fig 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values**



FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>

**Fig 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values**

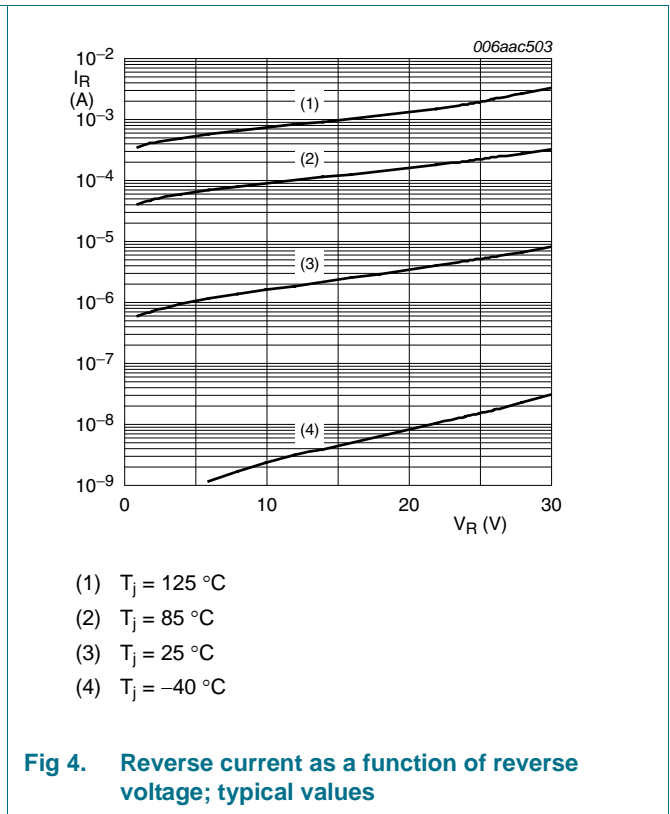
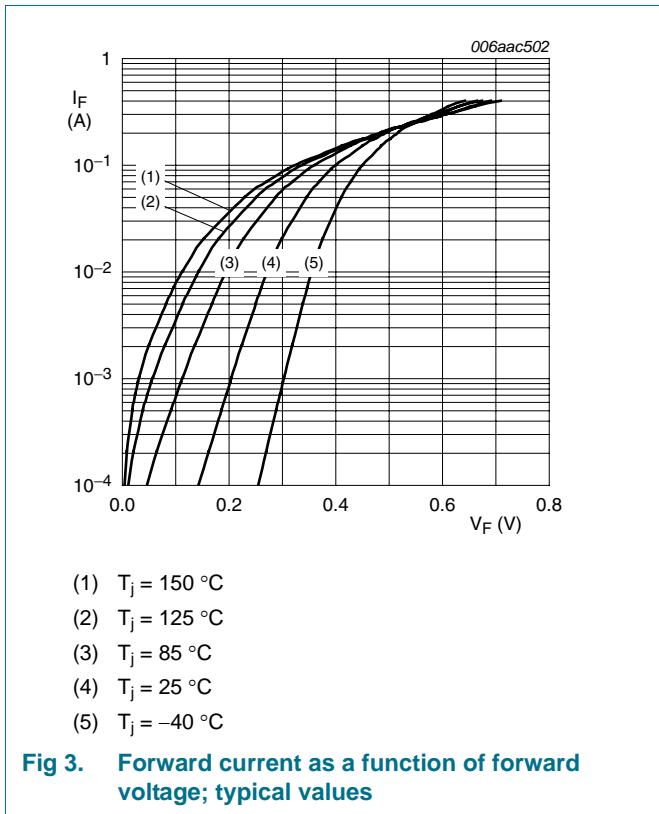
**7. Characteristics**

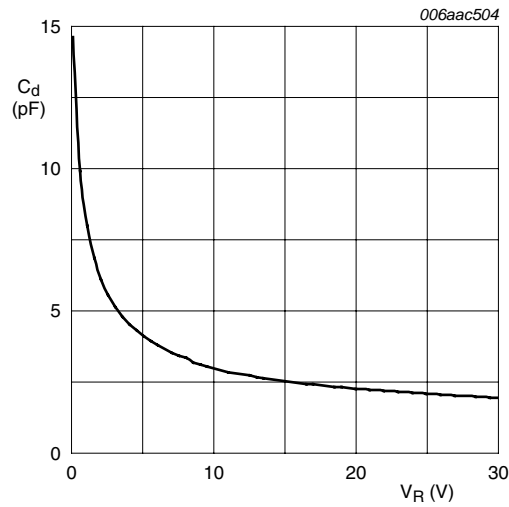
**Table 7. Characteristics**

$T_{amb} = 25\text{ }^\circ\text{C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_F$	forward voltage		[1]			
		$I_F = 0.1\text{ mA}$	-	145	-	mV
		$I_F = 1\text{ mA}$	-	210	-	mV
		$I_F = 10\text{ mA}$	-	280	350	mV
		$I_F = 100\text{ mA}$	-	405	-	mV
$I_R$	reverse current	$V_R = 10\text{ V}$	-	2	10	$\mu\text{A}$
$C_d$	diode capacitance	$V_R = 1\text{ V}; f = 1\text{ MHz}$	-	8	-	pF

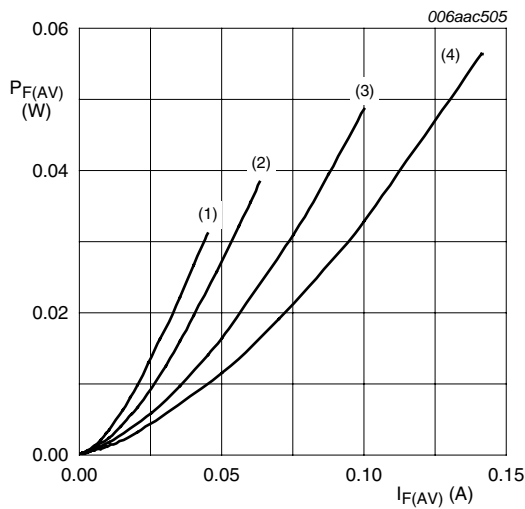
[1] Pulse test:  $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02$ .





$f = 1 \text{ MHz}; T_{\text{amb}} = 25 \text{ }^\circ\text{C}$

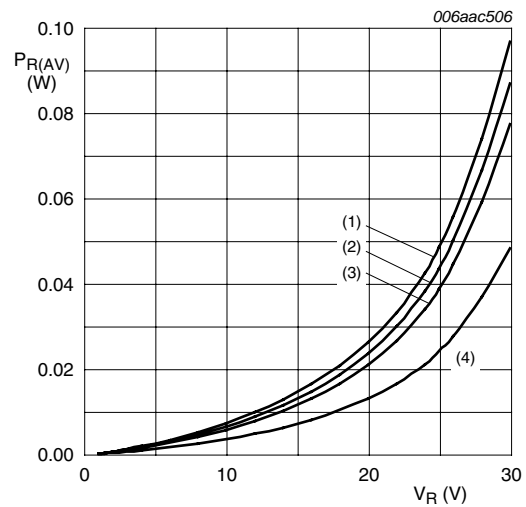
**Fig 5. Diode capacitance as a function of reverse voltage; typical values**



$T_j = 150 \text{ }^\circ\text{C}$

- (1)  $\delta = 0.1$
- (2)  $\delta = 0.2$
- (3)  $\delta = 0.5$
- (4)  $\delta = 1$

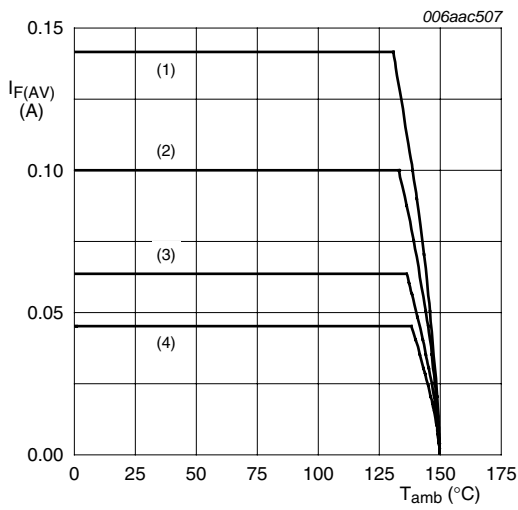
**Fig 6. Average forward power dissipation as a function of average forward current; typical values**



$T_j = 125 \text{ }^\circ\text{C}$

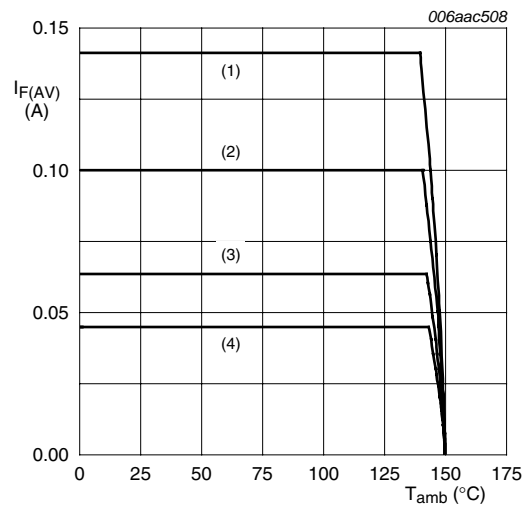
- (1)  $\delta = 1; \text{DC}$
- (2)  $\delta = 0.9; f = 20 \text{ kHz}$
- (3)  $\delta = 0.8; f = 20 \text{ kHz}$
- (4)  $\delta = 0.5; f = 20 \text{ kHz}$

**Fig 7. Average reverse power dissipation as a function of reverse voltage; typical values**



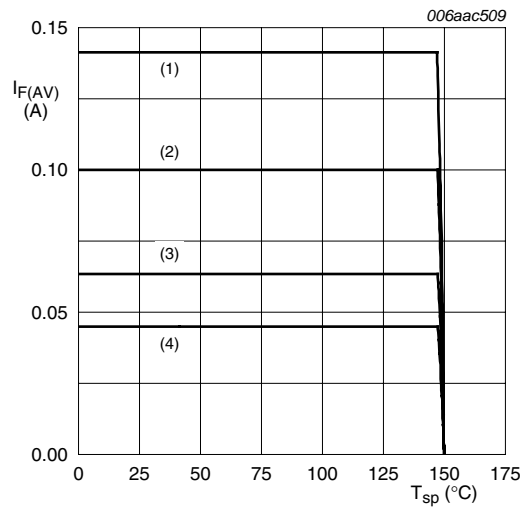
FR4 PCB, standard footprint  
 $T_j = 150\text{ °C}$   
 (1)  $\delta = 1$ ; DC  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

**Fig 8. Average forward current as a function of ambient temperature; typical values**



FR4 PCB, mounting pad for cathode  $1\text{ cm}^2$   
 $T_j = 150\text{ °C}$   
 (1)  $\delta = 1$ ; DC  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

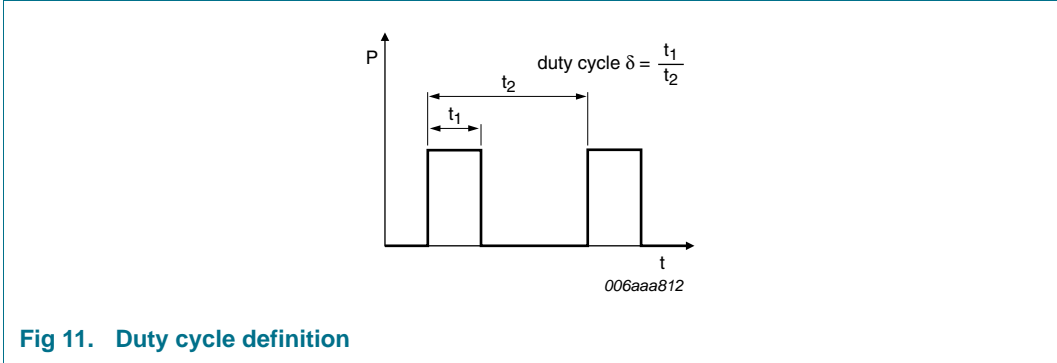
**Fig 9. Average forward current as a function of ambient temperature; typical values**



$T_j = 150\text{ °C}$   
 (1)  $\delta = 1$ ; DC  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

**Fig 10. Average forward current as a function of solder point temperature; typical values**

**8. Test information**



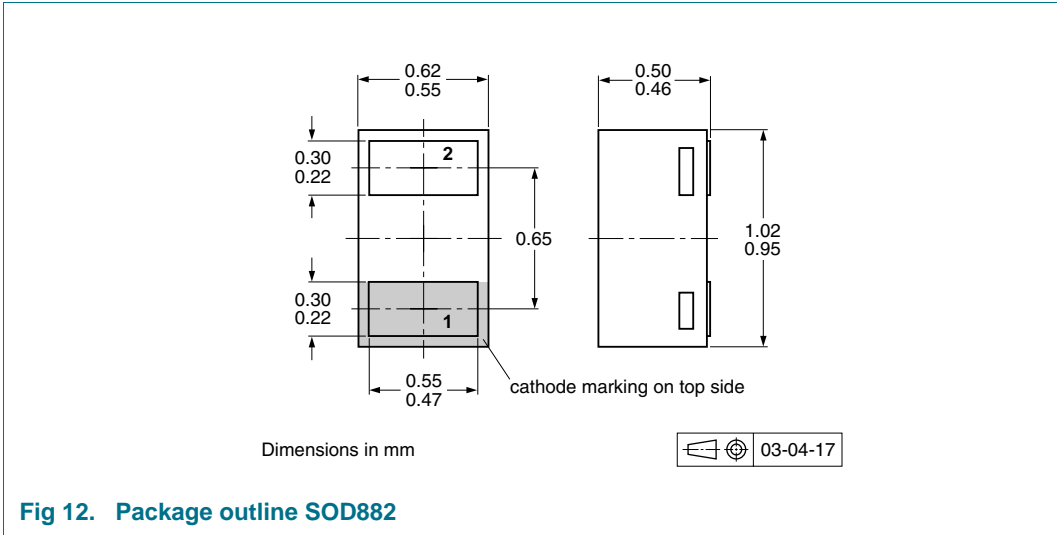
**Fig 11. Duty cycle definition**

The current ratings for the typical waveforms as shown in [Figure 8](#), [9](#) and [10](#) are calculated according to the equations:  $I_{F(AV)} = I_M \times \delta$  with  $I_M$  defined as peak current,  $I_{RMS} = I_{F(AV)}$  at DC, and  $I_{RMS} = I_M \times \sqrt{\delta}$  with  $I_{RMS}$  defined as RMS current.

**8.1 Quality information**

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

**9. Package outline**



**Fig 12. Package outline SOD882**



## 10. Packing information

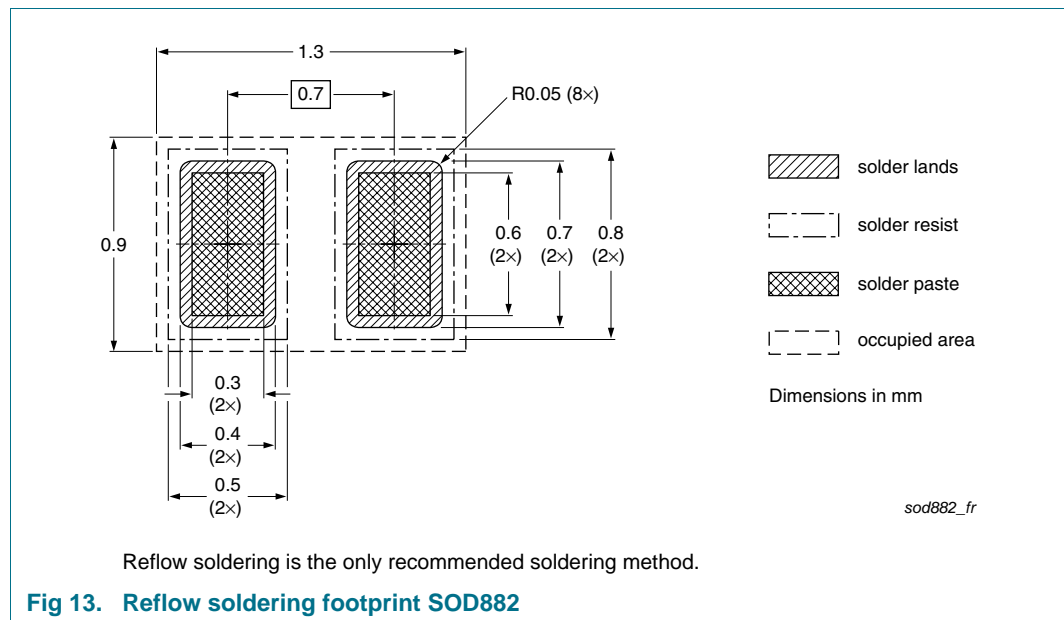
**Table 8. Packing methods**

The indicated -xxx are the last three digits of the 12NC ordering code.<sup>[1]</sup>

Type number	Package	Description	Packing quantity
RB521CS30L	SOD882	2 mm pitch, 8 mm tape and reel	10000
			-315

[1] For further information and the availability of packing methods, see [Section 14](#).

## 11. Soldering



## 12. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
RB521CS30L v.1	20110124	Product data sheet	-	-

## 13. Legal information

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Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".

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